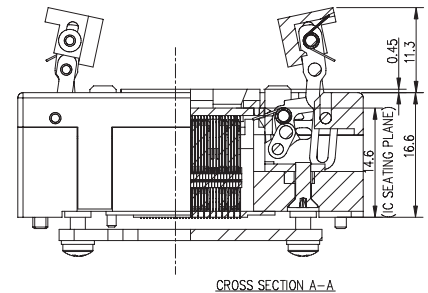
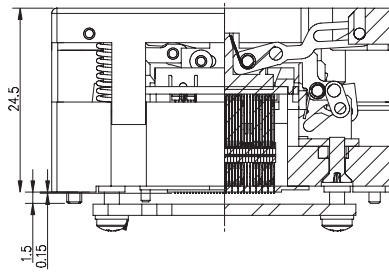
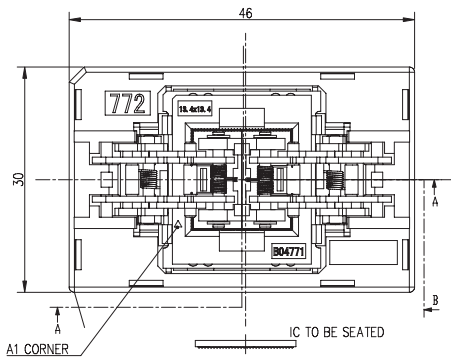




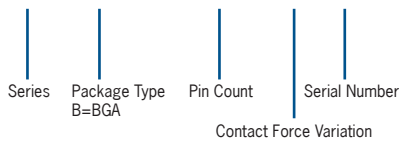
772 SERIES OPEN TOP CSP

- 0.4mm pitch for large array
- Compression surface mount
- Support up to 34x34 ball matrix
- Z-axis compliant buckling beam contact provides stable contact performance independent of solder ball height and composition
- Sharp edge of dual-point contact tip provides high electrical performance, minimizing ball damage
- Staggered fan out footprint for PCB design consideration
- Advanced latching system provide the ability to handle very thin package, limiting package warp



DESCRIPTION & ORDERING INFORMATION

772 - X 04 XXX - X XX



MATERIALS & SPECIFICATIONS

- Body Materials: PES, PEI, LCP or Equivalent
- Contact Material: Beryllium Copper Alloy
- Contact Plating: Gold
- Contact Force: 13 gram average
- Contact Resistance: 200~300 mΩ
- Capacitance:
- Temperature Rating: 150°C
- Durability: 10,000 cycles min.

Pitch e (mm)	Package Size (mm)	Pin Matrix	Max.Pin Count	Ball Dia. (mm)	Ball Height (mm)	Part Number
0.4	6.2X12.6	14X30	420	0.25	0.17	772-B04420-XXX
	12.6X12.6	30X30	900	0.23	0.17	772-B04900-XXX
	13.4X13.4	32X32	1024	0.25	0.17	772-B041024-XXX
	14X14	33X33	1089	0.25	0.16	772-B041089-XXX